

372. (Added) A structure, according to claim 334, wherein:

the second substrate is a multi-layer interconnection substrate.

373. (Added) A structure, according to claim 333, wherein:

the elongated electrical conductor extending from the locations of the surface of the first substrate comprises a wire.

#### REMARKS

Support for the added claims 319-373 is found throughout the specification and in US application serial number 07/685,368 filed on Oct. 19, 1992 incorporated by reference at page 7, lines 6-8 from the bottom, now issued as US 5,371,654 on December 6, 1994.

Claims 319-373 added herein are substantially identical to the claims of US 6,274,823 B1 which has an earliest claimed priority date of November 16, 1993. The present application is a continuation of US Application Serial Number 08/872,579, filed on 6/11/1997, now issued as US 6,334,247 B1 which is a divisional of US Application Serial Number 08/754,869, filed on November 22, 1996, now issued as US 5,821,763 on October 13, 1998, which is a continuation of US Application Serial Number 08/055,485, filed on April 30, 1993 and now issued as US 5,635,846 on June 3, 1997. Therefore, US 5,371,654 and US 5,635,846 are both 35 USC 102(e) references against US 6,274,823 B1.

Support for added claims 319-373 is found through the specification. Nonlimiting specific exemplary support for added claims 319-373 is in the figures of U.S. 5,371,654 incorporated by reference in the present application and the figures of the present application.

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Respectfully submitted,

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